INTEGRATED CIRCUITS

DATA SHEET

PCK2509S

50-150 MHz 1:9 SDRAM clock driver

Product specification





50-150 MHz 1:9 SDRAM clock driver

PCK2509S

FEATURES

 Phase-Locked Loop Clock distribution for PC100/PC133 SDRAM applications

- Spread Spectrum clock compatible
- Operating frequency 50 to 150 MHz
- (t_{phase error} jitter) at 100 to 133 MHz = ±50 ps
- Jitter (peak-peak) at 100 to 133 MHz = \pm 80 ps
- Jitter (cycle-cycle) at 100 to 133 MHz = 65 ps
- Pin-to-pin skew < 200 ps
- Available in plastic 24-Pin TSSOP
- Distributes one clock input to one bank of ten outputs
- External Feedback (FBIN) terminal Is used to synchronize the outputs to the clock input
- On-Chip series damping resistors
- No external RC network required
- Operates at 3.3 V
- Inputs compatible with 2.5 V and 3.3 V ranges

DESCRIPTION

The PCK2509S is a high-performance, low-skew, low-jitter, phase-locked loop (PLL) clock driver. It uses a PLLto precisely align, in both frequency and phase, the feedback (FBOUT) output to the clock (CLK) input signal. It is specifically designed for use with synchronous DRAMs. The PCK2509S operates at 3.3 V $\rm V_{CC}$ and is input compatible with both 2.5 V and 3.3 V input voltage ranges. It also provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of five outputs and one bank of four outputs provide nine low-skew, low-jitter copies of CLK. Output signal duty cycles are

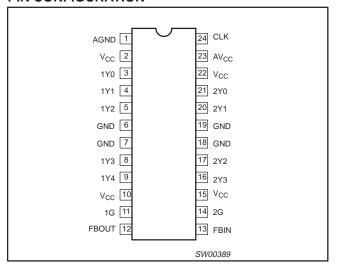
adjusted to 50 percent, independent of the duty cycle at CLK. Each bank of outputs can be enabled or disabled separately via the control (1G and 2G) inputs. When the G inputs are high, the outputs switch in phase and frequency with CLK; when the G inputs are low, the outputs are disabled to the logic–low state.

Unlike many products containing PLLs, the PCK2509S does not require external RC networks. The loop filter for the PLL is included on-chip, minimizing component count, board space, and cost.

Because it is based on PLL circuitry, the PCK2509S requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization time is required, following power up and application of a fixed-frequency, fixed-phase signal at CLK, and following any changes to the PLL reference or feedback signals. The PLL can be bypassed for test purposes by strapping AV_{CC} to ground.

The PCK2509S is characterized for operation from 0°C to +70°C.

PIN CONFIGURATION



ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER
24-Pin Plastic TSSOP	0°C to +70°C	PCK2509S PW	SOT355-1

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PIN DESCRIPTIONS

PIN NUMBER	SYMBOL	TYPE	NAME, FUNCTION, and DIRECTION
1	AGND	GND	Analog ground. AGND provides the ground reference for the analog circuitry.
2, 10, 15, 22	V _{CC}	PWR	Power supply
3, 4, 5, 8, 9	1Y (0-4)	OUT	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 1Y(0–4) is enabled via the1G input. These outputs can be disabled to a logic LOW state by de-asserting the 1G control input. Each output has an integrated 25 Ω series-damping resistor.
6, 7, 18, 19	GND	GND	Ground
11	1G	IN	Output bank enable. 1G is the output enable for outputs 1Y(0–4). When 1G is LOW, outputs 1Y(0–4) are disabled to a logic LOW state. When 1G is HIGH, all outputs 1Y(0–4) are enabled and switch at the same frequency as CLK.
12	FBOUT	OUT	Feedback output. FBOUT is dedicated for external feedback. It switches at the same frequency as CLK. When externally wired to FBIN, FBOUT completes the feedback loop of the PLL. FBOUT has an integrated 25 Ω series-damping resistor.
13	FBIN	IN	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be hard-wired to FBOUT to complete the PLL. The integrated PLL synchronizes CLK and FBIN so that there is nominally zero phase error between CLK and FBIN.
14	2G	IN	Output bank enable. 2G is the output enable for outputs 2Y(0–3). When 2G is LOW, outputs 2Y(0–3) are disabled to a logic LOW state. When 2G is HIGH, all outputs 2Y(0–3) are enabled and switch at the same frequency as CLK.
16, 17, 20, 21	2Y (0-3)	OUT	Clock outputs. These outputs provide low-skew copies of CLK. Output bank 2Y(0–3) is enabled via the 2G input. These outputs can be disabled to a logic LOW state by de-asserting the 2G control input. Each output has an integrated 25 Ω series-damping resistor.
23	AV _{CC}	PWR	Analog power supply. AV_{CC} provides the power reference for the analog circuitry. In addition, AV_{CC} can be used to bypass the PLL for test purposes. When AV_{CC} is strapped to ground, PLL is bypassed and CLK is buffered directly to the device outputs.
24	CLK	IN	Clock input. CLK provides the clock signal to be distributed by the PCK2509S clock driver. CLK is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLK must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid CLK signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to its reference signal.

FUNCTION TABLE

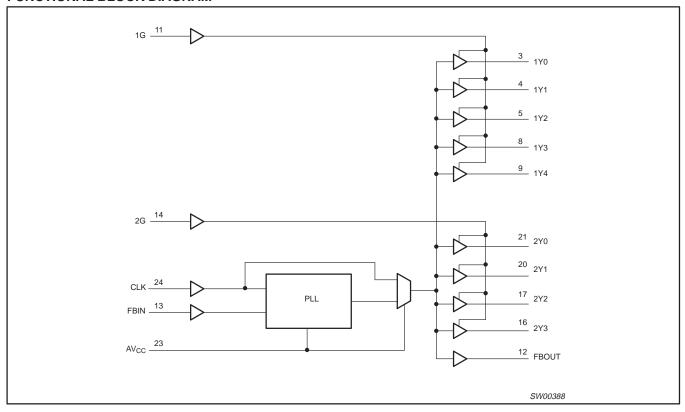
	INPUTS		OUTPUTS			
1G	2G	CLK	1Y (0-4)	2Y (0-3)	FBOUT	
Х	Х	L	L	L	L	
L	L	Н	L	L	Н	
L	Н	Н	L	Н	Н	
Н	L	Н	Н	L	Н	
Н	Н	Н	Н	Н	Н	

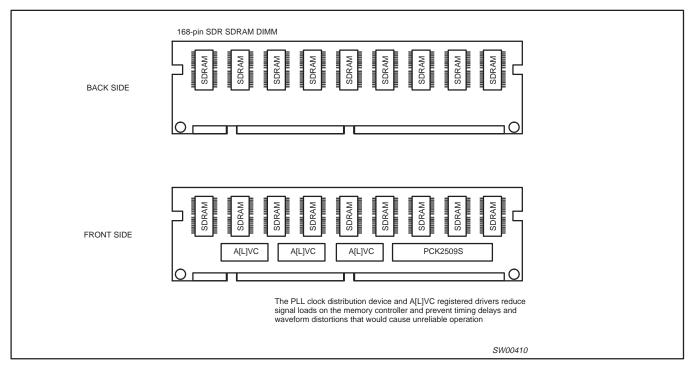
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FUNCTIONAL BLOCK DIAGRAM





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ABSOLUTE MAXIMUM RATINGS1

In accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITION	L	IMITS	UNIT
STWIBUL	PARAMETER	CONDITION	MIN	MAX	UNIT
AV _{CC}	Supply voltage range	Note 2		< V _{CC} + 0.7	V
V _{CC}	Supply voltage range		-0.5	+4.6	V
I _{IK}	Input clamp current	V ₁ < 0		- 50	mA
VI	Input voltage range	Note 3	-0.5	6.5	V
lok	Output clamp current	$V_O > V_{CC}$ or $V_O < 0$		±50	mA
V _O	Output voltage range	Notes 3, 4	-0.5	V _{CC} + 0.5	V
I _O	DC output source or sink current	$V_{O} = 0$ to V_{CC}		±50	mA
T _{STG}	Storage temperature range		-65	+150	°C
P _{TOT}	Power dissipation per package			700	mW

NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. AV_{CC} must not exceed V_{CC}
- 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- 4. This value is limited to 4.6 V maximum.

RECOMMENDED OPERATING CONDITIONS¹

SYMBOL	PARAMETER	CONDITIONS	LIM	ITS	UNIT
STWBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V _{CC} , AV _{CC}	Supply voltage		3	3.6	V
V _{IH}	HIGH level input voltage		2		V
V _{IL}	LOW level input voltage			0.8	V
V _I	Input voltage		0	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air		0	+70	°C

NOTE:

ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range (unless otherwise specified)

CVMDOL	DADAMETED		TEST CONDITIONS		LIMITS		
SYMBOL	PARAMETER	AV _{CC} , V _{CC} (V)	MIN	TYP	MAX	UNIT	
V _{IK}	Input clamp voltage	3	$I_I = -18mA$			-1.2	V
		MIN to MAX	$I_{OH} = -100 \mu A$	V _{CC} - 0.2			
V _{OH}	HIGH level output voltage	3	$I_{OH} = -12mA$	2.1			V
		3	$I_{OH} = -6mA$	2.4			
		MIN to MAX	I _{OL} = 100μA	-		0.2	
V _{OL}	LOW level output voltage	3	I _{OL} = 12mA	-		0.8	V
		3	$I_{OL} = 6mA$	_		0.55	
I _I	Input current	3.6	$V_I = V_{CC}$ or GND			±5	μΑ
Icc	Quiescent supply current	3.6	$V_I = V_{CC}$ or GND; $I_O = 0$, outputs: LOW or HIGH			10	μА
I _{CCA}	AV _{CC} power supply current	$AV_{CC} = 3.3$			30	50	μΑ
Δl _{CC}	Additional supply current per input pin	3.3 to 3.6	One input at $V_{CC} - 0.6V$; other inputs at V_{CC} or GND			500	μА
Cl	Input capacitance	3.3	$V_I = V_{CC}$ or GND		2.8		pF
Co	Output capacitance	3.3	V _O = V _{CC} or GND		5.4		pF

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^{1.} Unused inputs must be held high or low to prevent them from floating.

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TIMING REQUIREMENTS

Over recommended ranges of supply voltage and operating free-air temperature.

SYMBOL	PARAMETER	MIN	MAX	UNIT
f _{CLK}	Clock frequency	50	150	MHz
	Input clock duty cycle	40	60	%
	Stabilization time ¹		1	ms

NOTE:

SWITCHING CHARACTERISTICS

Over recommended ranges of supply voltage and operating free-air temperature, $C_L = 30 \text{ pF}^{-1}$

PARAMETER	FROM	то	V _{CC} , AV	_{CC} = 3.3 \	/ ±0.3 V	UNIT
PARAMETER	(INPUT)/CONDITION	(OUTPUT)	MIN	TYP	MAX	ONII
+ 2	CLKIN↑ = 100 MHz to 133 MHz	FBIN↑	-100		100	ps
t _{phase error} 2	CLKIN↑ = 66 MHz	FBIINT	-125		125	ps
t _{phase error} , – jitter ³	CLKIN↑ = 100 MHz to 133 MHz	FBIN↑	-50		50	ps
t _{SK(0)} ⁴	Any Y or FBOUT	Any Y or FBOUT			200	ps
jitter _(peak-peak)	CLKIN = 66 MHz to 133 MHz	Any Y or FBOUT	-80		80	
jitter (cycle-cycle)	CERTIN = 00 MINZ to 133 MINZ	Ally FOLFBOOT		65		ps
Duty cycle reference	F(CLKIN > 60 MHz)	Any Y or FBOUT	47		53	%
t _r	V _O = 0.4 to 2 V	Any Y or FBOUT	2.5		1	V/ns
t _f	V _O = 0.4 to 2 V	Any Y or FBOUT	2.5		1	V/ns

NOTES:

- 1. These parameters are not production tested.
- 2. This is considered as static phase error.
- Phase error does not include jitter. (tphase error = static tphase error jitter (cycle-cycle)).
 The t_{SK(0)} specification is only valid for equal loading of all outputs.

PARAMETER MEASUREMENT INFORMATION

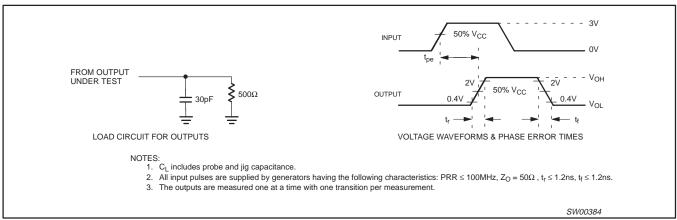


Figure 1. Load Circuit and Voltage Waveforms

Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable.

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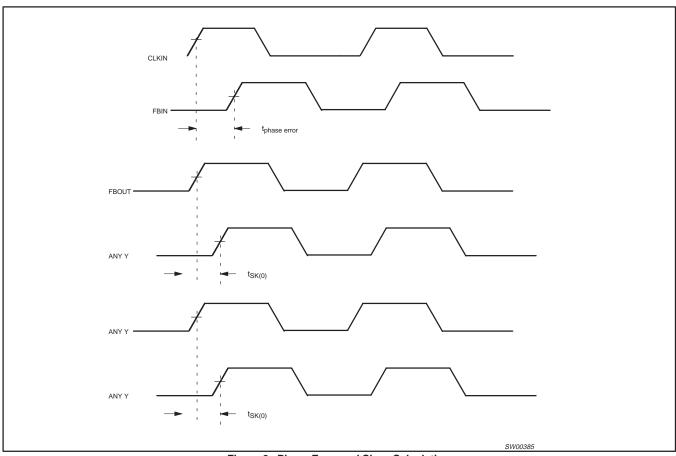


Figure 2. Phase Error and Skew Calculations

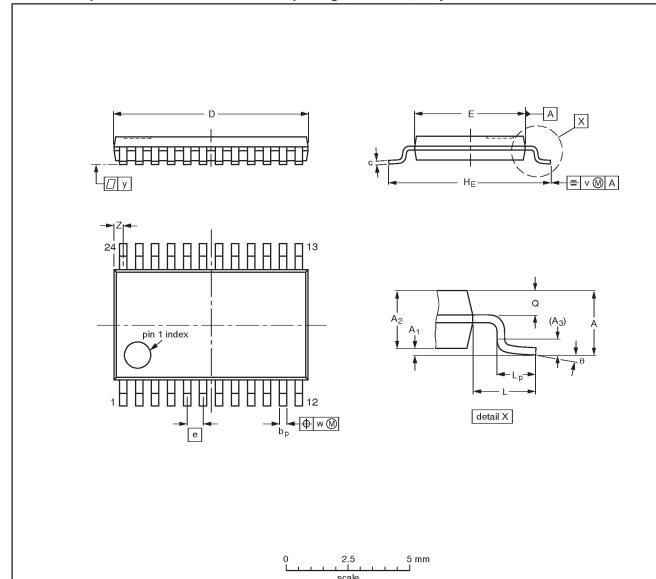
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TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT355-1		MO-153AD			93-06-16 95-02-04

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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